

June 1, 2018

Notice Concerning Issuance of the 501st, 502nd and 503rd Straight Bonds of Tohoku Electric Power Co., Inc.

We hereby announce that the 501st, 502nd and 503rd Straight Bonds of Tohoku Electric Power Co., Inc. will be issued as described below.

Please note that the 501st and 502nd bond will be offered to institutional investors only, and the 503rd bond will be offered to individual investors only.

The 501st Straight Bond (institutional investors only)

1. Purpose of issuance: Proceeds will be used for capital expenditure and bond redemption

2. Type of bond: Straight bond (with general mortgage)

3. Aggregate

principal amount: 20 billion yen
4. Denomination: 1 million yen

5. Schedule: Date of offer June 1, 2018

Subscription date June 1, 2018
Closing date June 7, 2018
Date of issue June 7, 2018

6. Interest: 0.385% p.a.

(Yield to maturity: 0.385% p.a.)

7. Issue price: 100% of the denomination
8. Redemption price: 100% of the denomination
9. Period to maturity: 10 years (June 23, 2028)

10. Redemption method: Bullet maturity

11. Managers: Mizuho Securities Co., Ltd. (Lead manager)

Daiwa Securities Co. Ltd. SMBC Nikko Securities Inc. Shinkin Securities Co., Ltd.

12. Bond trustees: Mizuho Bank, Ltd.

Sumitomo Mitsui Banking Corporation

13. Bond rating: A (Rating and Investment Information, Inc.)

AA- (Japan Credit Rating Agency, Ltd.)

The 502nd Straight Bond (institutional investors only)

1. Purpose of issuance: Proceeds will be used for capital expenditure and bond redemption

2. Type of bond: Straight bond (with general mortgage)

3. Aggregate

principal amount: 10 billion yen 4. Denomination: 1 million yen

5. Schedule: Date of offer June 1, 2018

Subscription date June 1, 2018
Closing date June 7, 2018
Date of issue June 7, 2018

6. Interest: 0.749% p.a.

(Yield to maturity: 0.749% p.a.)

7. Issue price: 100% of the denomination
8. Redemption price: 100% of the denomination
9. Period to maturity: 20 years (May 25, 2038)

10. Redemption method: Bullet maturity

11. Managers: SMBC Nikko Securities Inc. (Lead manager)

Nomura Securities Co., Ltd.

Mitsubishi UFJ Morgan Stanley Securities Co., Ltd.

Tokai Tokyo Securities Co., Ltd.

12. Bond trustees: Mizuho Bank, Ltd.

Sumitomo Mitsui Banking Corporation

13. Bond rating: A (Rating and Investment Information, Inc.)

AA- (Japan Credit Rating Agency, Ltd.)

The 503rd Straight Bond (individual investors only)

1. Purpose of issuance: Proceeds will be used for capital expenditure and bond redemption

2. Type of bond: Straight bond (with general mortgage)

3. Aggregate

principal amount: 10 billion yen

4. Denomination: 100 thousand yen

5. Schedule: Date of offer June 4, 2018

Subscription date June 21, 2018
Closing date June 22, 2018

Date of issue June 22, 2018

6. Interest: 0.14% p.a.

(Yield to maturity: 0.14% p.a.)

7. Issue price: 100% of the denomination8. Redemption price: 100% of the denomination

9. Period to maturity: 3 years (June 25, 2021)

10. Redemption method: Bullet maturity

11. Manager: Daiwa Securities Co. Ltd.

12. Bond trustees: Mizuho Bank, Ltd.

Sumitomo Mitsui Banking Corporation

13. Bond rating: A (Rating and Investment Information, Inc.)

AA- (Japan Credit Rating Agency, Ltd.)

14. Dealers: Daiwa Securities Co. Ltd.

Nomura Securities Co., Ltd. SMBC Nikko Securities Inc. Mizuho Securities Co., Ltd.

Mitsubishi UFJ Morgan Stanley Securities Co., Ltd.

Tokai Tokyo Securities Co., Ltd.

Okasan Securities Co., Ltd. Marusan Securities Co., Ltd. Toyo Securities Co., Ltd.

Okasan Niigata Securities Co., Ltd.

Daishi Securities Co., Ltd. Mito Securities Co., Ltd. SBI SECURITIES Co., Ltd.